

UNI-NAP 1 SF

Uni-Nap 1-SF is a polishing material exhibiting unique pore structure and superior surface characteristics. Its layered construction translates flatness to the work surface while enabling ultra-fine angstrom level finishes. Uni-Nap 1-SF has excellent surface wear characteristic and resistance to temperature and humidity changes. It works with machine oil, alkaline chemicals and other mineral oils.

APPLICATION

Uni-Nap 1-SF can be used with final polishing in CMP device fabrication, silicon wafers, GAAS wafers, photo masks, nickel-plated and glass memory disks.

BENEFITS

- Chemical, temperature, and humidity resistivity
- Available in a wide array of sizes up to 54" with PSA coating
- Fine angstrom finishing

PHYSICAL CHARACTERISTICS

TEST	SPECIFICATION
Weight (g/m ²)	480 - 680
Thickness (mm)	1.45 - 1.61
Density (g/cm ³)	0.33 - 0.43
Shore C Hardness	57 - 67
NAP layer thickness (µm)	450 - 610
Pore Size (µm)	25 - 75
Compressibility (%)	1.5 - 3.5
Recovery (%)	60 - 90

AVAILABILITY

Variety of sizes